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Larson

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(54) **SOCKET TEST DEVICE FOR DETECTING CHARACTERISTICS OF SOCKET SIGNALS**

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(58) Field of Search 324/158.1, 73.1, 324/755, 537, 538, 765; 439/912, 66, 70, 482; 714/48, 733, 736, 738; 365/201

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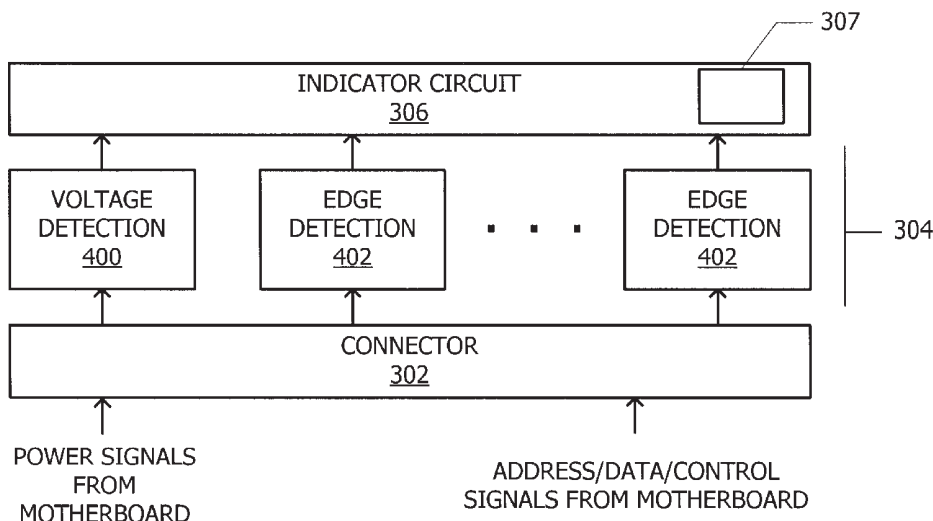
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(57) **ABSTRACT**

A test device to determine the operational behavior of a memory module socket may include a connector configured to mate with a memory module socket, a signal detection circuit to detect a power characteristic of a first signal, and an edge detection circuit to detect a transition of a second signal. The test device may provide continuity verification for signals passing through the memory module socket. In another implementation, the test device may include a connector, a signal capture circuit to detect and digitally sample a signal, and a memory to store a value representative of the sampled signal. This device may use a digital signal processor (as the signal capture circuit) to analyze the sampled signal. Test devices may also include an indicator circuit to indicate operation of the signal detection, edge detection, or signal capture circuits.

18 Claims, 3 Drawing Sheets



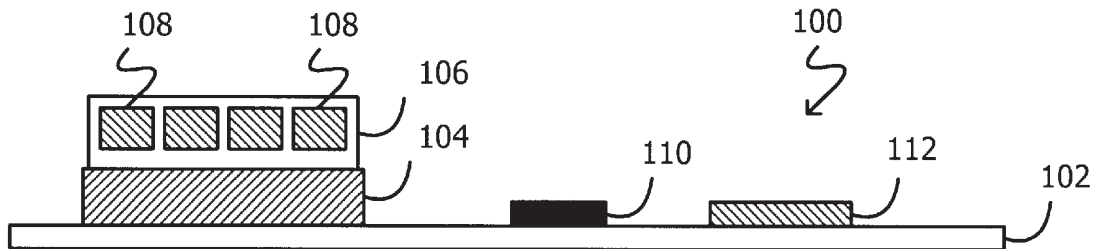


FIG. 1
(Prior Art)

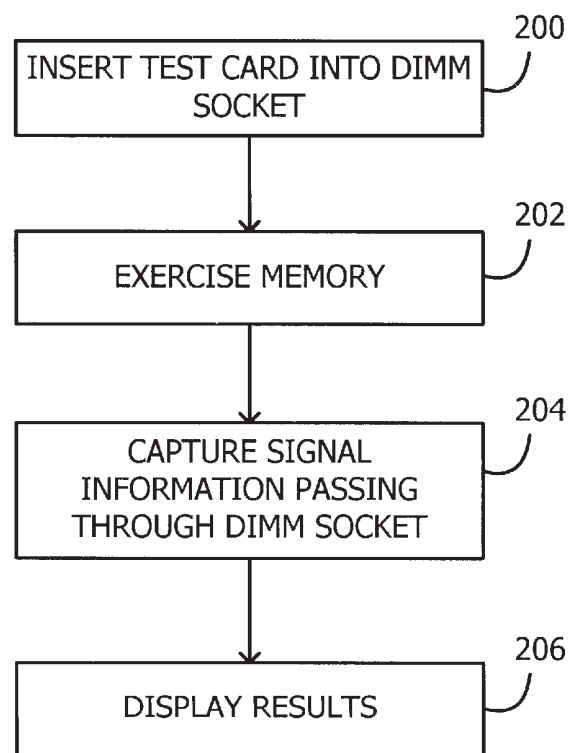
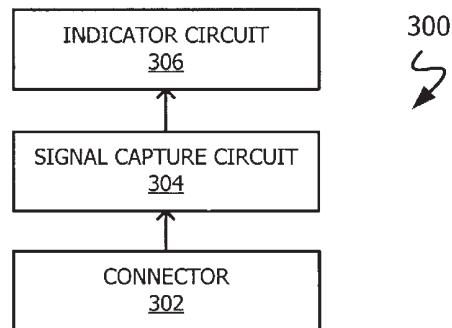
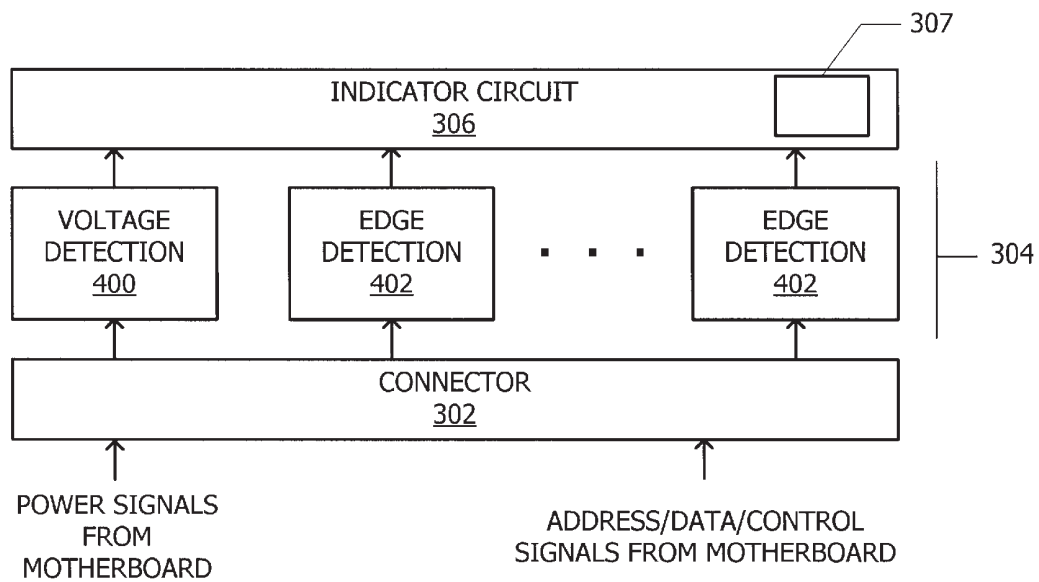
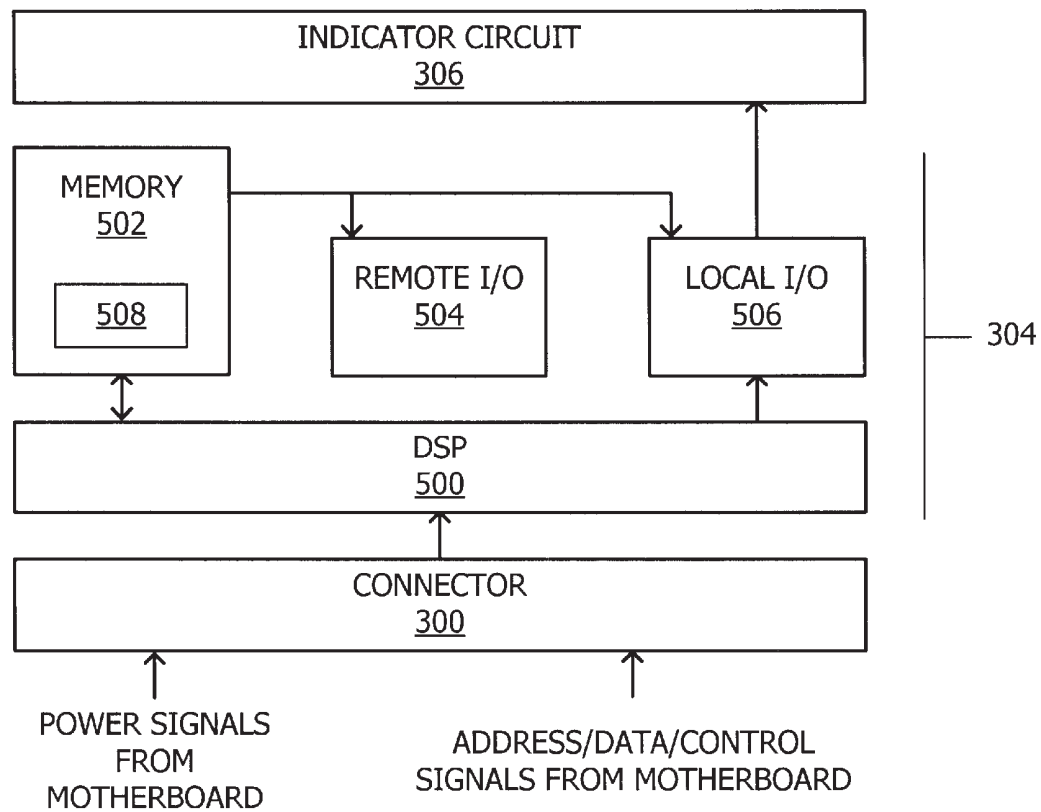


FIG. 2

**FIG. 3****FIG. 4**

**FIG. 5**

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SOCKET TEST DEVICE FOR DETECTING CHARACTERISTICS OF SOCKET SIGNALS

BACKGROUND

The invention relates generally to the field of electrical component testing and, more particularly, to continuity and integrity testing of signals through an electrical connector.

Many current computer systems use a system circuit board (a motherboard) to host the system's central processing unit, bus bridge circuitry, and other system critical circuitry. Motherboards also typically include a number of sockets (e.g., card edge connectors) through which additional components such as random access memory (RAM), universal serial bus (USB) devices, audio and video devices, network control circuitry, and modems may be coupled. A failure on any pin in any connector may affect the entire computer system.

With today's high speed signals, even a small amount of corrosion or other defect in a socket may cause a component or system failure. Current techniques to locate mechanical failures include probing individual pins within a socket's connector with an oscilloscope or digital logic analyzer. These techniques are both time consuming and may not test the system under operational conditions. Thus, it would be beneficial to provide a mechanism for testing socket connectors by performing signal continuity and integrity testing in an operational setting.

SUMMARY

In one embodiment the invention provides a test device including a connector configured to mate with a memory module socket (the connector having pins to receive signals from the socket), a signal detection circuit to detect a power characteristic of a first signal (for example, voltage or current level), and an edge detection circuit to detect a transition of a second signal (for example, a high-to-low state or a low-to-high state transition). The embodiment may also include an indication circuit to indicate the operation of the detection circuit and the edge detection circuit.

In another embodiment, the invention provides a test device including a connector configured to mate with a memory module socket (the connector having pins to receive signals from the socket), a signal capture circuit to detect and digitally sample a signal on at least one of the pins, and a memory to store a value representative of the sampled signal. This embodiment may also include a routine stored in the memory to direct the signal capture circuit to perform signal integrity analysis on the sampled signal, and/or an indicator circuit to indicate operation of the signal capture circuit, and/or an output circuit to communicate the representation of the sampled signal to a display unit. The integrity analysis may include, for example, signal voltage levels and/or signal transition time analysis.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 shows a side view of an illustrative computer system.

FIG. 2 shows a testing technique in accordance with one embodiment of the invention.

FIGS. 3 shows a test device in accordance with one embodiment of the invention.

FIG. 4 shows a test device in accordance with another embodiment of the invention.

FIG. 5 shows a test device in accordance with yet another embodiment of the invention.

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DETAILED DESCRIPTION

Techniques (including methods and devices) to test the functionality of an electrical connector are described. The following embodiments, described in terms of a dual in-line memory module (DIMM) socket, are illustrative of the inventive concept only and are not to be considered limiting in any respect.

Referring to FIG. 1, an illustrative computer system **100** may include motherboard **102**, DIMM socket **104**, DIMM **106** (having memory circuits **108**), central processing unit **110**, and other circuitry **112**. Diagnostic operations, during or after system **100** assembly/manufacture, may indicate a memory failure. Such a failure may be the result of motherboard **102** failure, dysfunctional socket **104**, or dysfunctional DIMM **106**. For example, motherboard **102** may be a memory board test system designed to systematically generate memory read and memory write signals to memory circuits **108**. (That is, under software control central processing unit **110** may command a series of memory operations to determine if memory module **106** functions properly.)

One technique in accordance with the invention to determine if the failure is due to socket **104** is illustrated in FIG. 2. A test device (described below) may be inserted into socket **104** (at **200**) and system **100** (e.g., central processing unit **110** under software control) commanded to write to memory circuits **108** as if DIMM **106** were coupled to motherboard **102** through socket **104** (at **202**). During memory write operations at **202**, the test device captures information about the signals it receives through socket **104** (at **204**) and displays the results (at **206**).

Referring to FIG. 3, test device **300** in accordance with one embodiment of the invention may include a connector **302** to couple itself to motherboard **102** through socket **104**, a signal capture circuit **304** to capture and/or process signals received through connector **302** (from motherboard **102**), and an indicator circuit **306** to display the results of the signal capture operations at **204**.

Connector **302** may be any connector compatible with socket **104**. For example, if socket **104** is a peripheral component interconnect (PCI) socket, an industry standard architecture (ISA) socket, extended industry standard architecture (EISA) socket, or a single in-line memory module (SIMM) socket, connector **302** must conform to the PCI, ISA, EISA or SIMM standard respectively. For purposes of illustration only, socket **104** and connector **302** may conform to the 168 pin DIMM socket standard as described in the Joint Electron Device Engineering Council (JEDEC) standard, No. 21-C (Published by the Electronics Industries Association). In standard No. 21-C, approximately 49 pins are dedicated to power signals or are not connected, leaving approximately 149 pins dedicated to data and/or address and/or control signals.

Signal capture circuit **304** may include any necessary circuitry to detect and, possibly, process signals it receives from motherboard **102** through socket **104** and connector **302** (see discussion below).

Indicator circuit **306** may be any circuitry capable of indicating or displaying the results generated by signal capture circuit **304**. In one embodiment of the invention, indicator circuit **306** may include light emitting diodes (LEDs), **307** (FIGS. 4 and 5) to indicate continuity between motherboard **102** and test device **300** via socket **104**/connector **302**. For example, the LED **307** (FIGS. 4 and 5) may be illuminated if the pin (in connector **302**) it is coupled to exhibits electrical continuity with its complementary pin

in socket **104**. In another embodiment of the invention, indicator circuit **306** may include an electrical interface, **307** (FIGS. **4** and **5**) for displaying signal capture circuit **304** output on a cathode ray tube (CRT) or liquid crystal display (LCD) device. In yet another embodiment, indicator circuit **306** may include an electrical interface **307** (FIGS. **4** and **5**) for communicating signal capture circuit **304** output to another device such as a computer system or storage device.

In one embodiment of the invention (see FIG. **4**), signal capture circuit **304** may include voltage detection **400** and edge detection **402** circuitry. Voltage detection circuitry **400** may be coupled to those pins in connector **302** through which motherboard **102** provides power (e.g., ground, VCC, VDD, and VSS voltages). Voltage detection circuitry **400** may include circuitry to detect a variety of voltage levels such as, for example, ± 3.0 volts (V), ± 3.3 V, ± 5.0 V ± 12 V. One illustrative voltage level detection circuit may include an operational amplifier having the specified voltage level (e.g., 3.3 V) as one input and the signal from socket **104**/connector **300** as the other input. Signal capture circuit **304** may also include edge detection circuitry **402** (e.g., D or J-K flip-flops) to detect edge transitions (high to low, and low to high) on address, data, and control pins of connector **302**. If the appropriate voltage or signal transitions are detected, signal capture circuit **304** may provide an indication to indicator circuit **306** which may then display the results as described above.

In another embodiment of the invention (see FIG. **5**), signal capture circuit **304** may include digital signal processor (DSP) **500**, memory **502**, remote input-output (I/O) circuit **504**, and local output circuit **506**. DSP **500** may be designed to sample and digitize signals passing through socket **104** to connector **302**. For example, DSP **500** may execute routine **508** (stored in memory **502**) to sample all signals and store the sampled data into memory **502**. Routine **508** may further provide instructions to cause DSP **500** to analyze the sampled data to determine if the voltage levels and timing characteristics of the sampled signals fall within the appropriate ranges. In the case where socket **104** couples a 3 V or 3.3 V circuit, such as a 3/3.3 V DIMM, JEDEC Standard No. 8-A describes the voltage ranges deemed appropriate or acceptable.

Local output circuit **506** may provide signals to indicator circuit **306** so that results of DSP signal acquisition and analysis may be displayed to a user as described above. Routine **508** may also provide instructions to transmit the collected data to another device (e.g., a computer system) through remote I/O circuit **504**. Illustrative remote I/O circuits **504** include serial and parallel ports.

In the embodiment described above, DSP **500** samples every signal passing through socket **104** and connector **300**. If the number of signals or the sampling rate needed to characterize the signals (this, of course, depends upon the timing characteristics of the signals and will vary from system to system) is large, a single DSP device may be unable to perform the necessary tasks. In this case, two or more DSP devices may be used to accomplish the same task. Alternatively, power detection circuit **400** may be used to determine if the pins designated to supply voltage (through socket **104**) are continuous with connector **302** pins and DSP **500** may be used to only sample address, data, and control signals.

For each pin coupled from socket **104** to connector **300**, signal capture circuit **304** determines if socket **104** is operationally intact by measuring a signal and comparing the measured signal against some known value or range. Pins

designated to supply power (e.g., voltage) are relatively easy to test because the specified voltage is generally there (socket **104** is functional) or not there (socket **104** is nonfunctional). Similarly, pins dedicated to address, data, and command signals may be tested for continuity (e.g., edge detection) or for signal integrity (e.g., measured voltage levels and transition times). To determine signal integrity characteristics, those pins associated with signals that transition (e.g., from a high state to a low state or a low state to a high state) must be commanded to do so—generally by a device (e.g., processor **110**) on motherboard **102**.

Various changes in the materials, components, circuit elements, as well as in the details of the illustrated operational method are possible without departing from the scope of the claims. For instance, the illustrative systems of FIGS. **3**, **4**, and **5** are not limited to testing dual in-line memory modules; virtually any type of socket may be tested in accordance with the invention. In addition, acts in accordance with FIG. **2** may be performed by a programmable control device executing instructions organized into a program module (e.g., routine **508** or computer instructions executable by a device coupled to motherboard **102**). A programmable control device may be a computer processor or a custom designed state machine. Custom designed state machines may be embodied in a hardware device such as a printed circuit board comprising discrete logic, integrated circuits, or specially designed application specific integrated circuits (ASIC). Storage devices suitable for tangibly embodying program instructions include all forms of non-volatile memory including, but not limited to: semiconductor memory devices such as EPROM, EEPROM, and flash devices; magnetic disks (fixed, floppy, and removable); other magnetic media such as tape; and optical media such as CD-ROM disks.

What is claimed is:

1. A test device comprising:

a connector configured for insertion into a memory module socket, the connector having pins to receive signals from the socket, the signals comprising a first signal and a second signal;

a signal detection circuit, coupled to a first pin, to detect a power characteristic of the first signal to test the memory module socket;

an edge detection circuit, coupled to a second pin, to detect a transition of the second signal to test the memory module socket; and

an indicator circuit to indicate the operation of the detection circuit and the edge detection circuit.

2. The test device of claim 1, wherein the memory module socket comprises a dual in-line memory module socket.

3. The test device of claim 1, wherein the power characteristic comprises a voltage level.

4. The test device of claim 1, wherein the transition is a high-state to low-state signal transition.

5. The test device of claim 1, wherein the indicator circuit comprises a light emitting diode device.

6. The test device of claim 1, wherein the indicator circuit comprises a liquid crystal display device.

7. The test device of claim 1, wherein the connector is adapted to be inserted into the memory module socket.

8. The test device of claim 1, wherein the connector is adapted to be mated with the memory module socket, the memory module socket capable of receiving at least one memory device.

9. The test device of claim 8, wherein the connector is adapted to be mated with the memory module socket in place of the at least one memory device.

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10. A test device comprising:

a unit comprising a connector for receiving signals comprising a first signal and a second signal from a memory module socket, the unit further comprising a signal capture circuit to capture signals from the connector, the unit adapted to mate with the memory module socket,

the signal capture circuit adapted to detect a power characteristic of the first signal and to detect a transition of the second signal to test the memory module socket, the unit further comprising an indicator circuit to indicate an operation of the signal capture circuit.

11. The test device of claim **10**, wherein the signal capture circuit is adapted to compare the detected power characteristic with a known range.

12. The test device of claim **10**, wherein the signal capture circuit is adapted to measure a transition time of the second signal to determine signal integrity.

13. The test device of claim **10**, wherein the signal capture circuit is adapted to detect the power characteristic by determining if a voltage is in a known range.

14. The test device of claim **10**, wherein the connector is adapted to be inserted into the memory module socket.

15. The test device of claim **10**, wherein the connector is adapted to be mated with the memory module socket, the memory module socket capable of receiving at least one memory device.

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16. The test device of claim **15**, wherein the connector is adapted to be mated with the memory module socket in place of the at least one memory device.

17. A method of testing, comprising:

attaching a unit having a connector to a memory module socket, the connector to receive signals comprising a first signal and a second signal from the memory module socket;

providing a signal capture circuit to capture signals from the connector;

detecting, with the signal capture circuit, a power characteristic of the first signal to test the memory module socket;

detecting, with the signal capture circuit, a transition of the second signal to test the memory module socket; and

indicating operation of the signal capture circuit with an indicator circuit.

18. The method of claim **17**, wherein attaching the connector to the memory module socket is performed in place of a memory device capable of being inserted into the memory module socket.

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